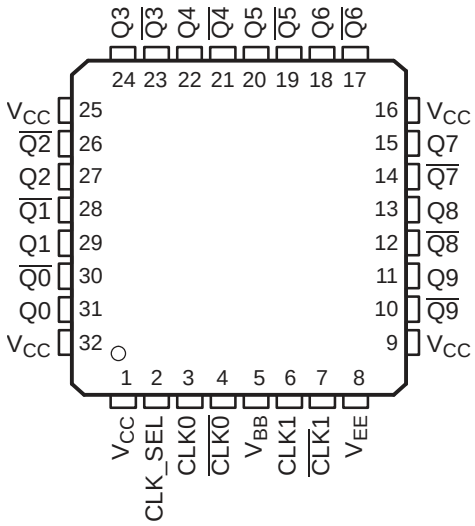
Low-Voltage 1:10 LVPECL/HSTL With Selectable Input Clock Driver

Check for Samples: CDCLVP110

FEATURES

- **Distributes One Differential Clock Input Pair LVPECL/HSTL to 10 Differential LVPECL Clock Outputs**
- **Fully Compatible With LVECL/LVPECL/HSTL**
- **Single Supply Voltage Required, ±3.3-V or ±2.5-V Supply**
- **Selectable Clock Input Through CLK_SEL**
- **Low-Output Skew (Typ 15 ps) for Clock-Distribution Applications**
- **VBB Reference Voltage Output for Single-Ended Clocking**
- **Available in a 32-Pin LQFP Package**
- **Frequency Range From DC to 3.5 GHz**
- **Pin-to-Pin Compatible With MC100 Series EP111, ES6111, LVEP111, PTN1111**

LQFP PACKAGE
(TOP VIEW)



DESCRIPTION

The CDCLVP110 clock driver distributes one differential clock pair of either LVPECL or HSTL (selectable) input, (CLK0, CLK1) to ten pairs of differential LVPECL clock (Q0, Q9) outputs with minimum skew for clock distribution. The CDCLVP110 can accept two clock sources into an input multiplexer. The CLK0 input accepts either LVECL/LVPECL input signals, while CLK1 accepts an HSTL input signal when operated under LVPECL conditions. The CDCLVP110 is specifically designed for driving 50-Ω transmission lines.

The VBB reference voltage output is used if single-ended input operation is required. In this case the VBB pin should be connected to $\overline{CLK0}$ and bypassed to GND via a 10-nF capacitor.

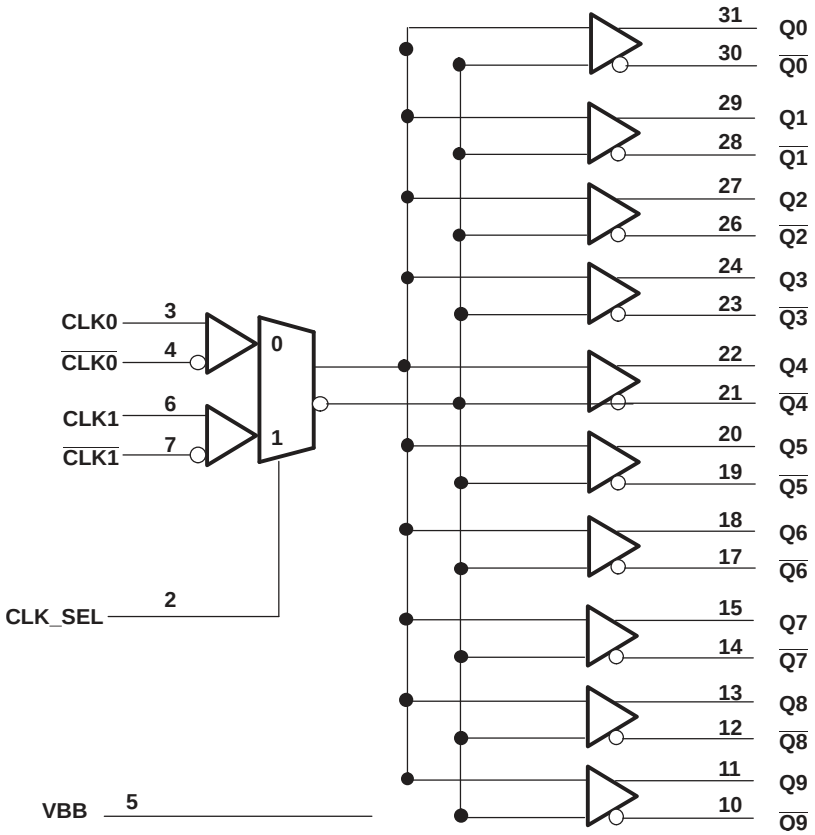
However, for high-speed performance up to 3.5 GHz, the differential mode is strongly recommended.

The CDCLVP110 is characterized for operation from –40°C to 85°C.

Table 1. FUNCTION TABLE

CLK_SEL	ACTIVE CLOCK INPUT
0	CLK0, $\overline{CLK0}$
1	CLK1, $\overline{CLK1}$

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.



TERMINAL FUNCTIONS

TERMINAL		DESCRIPTION
NAME	NO.	
CLK_SEL	2	Clock select. Used to select between CLK0 and CLK1 input pairs.
CLK0, $\overline{\text{CLK0}}$	3, 4	Differential LVECL/LVPECL input pair
CLK1, $\overline{\text{CLK1}}$	6, 7	Differential HSTL input pair
Q [9:0]	11, 13, 15, 18, 20, 22, 24, 27, 29, 31	LVECL/LVPECL clock outputs, these outputs provide low-skew copies of CLKn.
$\overline{\text{Q}}$[9:0]	10, 12, 14, 17, 19, 21,23, 26, 28, 30	LVECL/LVPECL complementary clock outputs, these outputs provide copies of $\overline{\text{CLKn}}$.
V_{BB}	5	Reference voltage output for single-ended input operation
V_{CC}	1, 9, 16, 25, 32	Supply voltage
V_{EE}	8	Device ground or negative supply voltage in ECL mode

ABSOLUTE MAXIMUM RATINGS(1)

		VALUE	UNIT
V_{CC}	Supply voltage	–0.3 to 4.6	V
V_I	Input voltage	–0.3 to V_{CC} + 0.5	V
V_O	Output voltage	–0.3 to V_{CC} + 0.5	V
I_{IN}	Input current	±20	mA
V_{EE}	Negative supply voltage	–0.3 to 4.6	V
I_{BB}	Sink/source current	–1 to 1	mA
I_O	DC output current	–50	mA
T_{stg}	Storage temperature range	–65 to 150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage (relative to V_{EE})	2.375	2.5/3.3	3.8	V
T_A (1)	Operating free-air temperature	–40		85	°C

(1) Operating junction temperature affects device lifetime. The continuous operation junction temperature is recommended to be at max 110°C. The device ac and dc parameters are specified up to 85°C ambient temperature. See the *PCB Layout Guidelines for CDCLVP110* application note, literature number SCAA057 for more details.

PACKAGE THERMAL IMPEDANCE

		TEST CONDITIONS	MIN	MAX	UNIT
Θ_{JA}	Thermal resistance junction to ambient(1)	0 LFM		74	°C/W
		150 LFM		66	°C/W
		250 LFM		64	°C/W
		500 LFM		61	°C/W
Θ_{JC}	Thermal resistance junction to case			39	°C/W

(1) According to JESD 51-7 standard.

LVECL DC ELECTRICAL CHARACTERISTICS

Vsupply: V_{CC} = 0 V, V_{EE} = -2.375 V to -3.8 V

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
I_{EE}	Supply internal current	Absolute value of current	–40°C	40		78	mA
			25°C	45		82	
			85°C	48		85	
I_{CC}	Output and internal supply current	All outputs terminated 50 Ω to V_{CC} – 2 V	–40°C			343	mA
			25°C			370	
			85°C			380	
I_{IN}	Input current		–40°C, 25°C, 85°C			150	µA
V_{BB}	Internally generated bias voltage	For V_{EE} = –3 to -3.8 V, I_{BB} = -0.2 mA	–40°C, 25°C, 85°C	–1.45	–1.3	–1.15	V
		V_{EE} = –2.375 to –2.75 V, I_{BB} = –0.2 mA	–40°C, 25°C, 85°C	–1.4	–1.25	–1.1	
V_{IH}	High-level input voltage (CLK_SEL)		–40°C, 25°C, 85°C	–1.165		–0.88	V
V_{IL}	Low-level input voltage (CLK_SEL)		–40°C, 25°C, 85°C	–1.81		–1.475	V
VIN_{PP}	Input amplitude (CLK0, $\overline{CLK0}$)	Difference of input 9 V_{IH}–V_{IL} , See Note (1)	–40°C, 25°C, 85°C	0.5		1.3	V
V_{CM}	Common-mode voltage (CLK0, $\overline{CLK0}$)	Cross point of input 9 average (V_{IH}, V_{IL})	–40°C, 25°C, 85°C	V_{EE} + 0.975		–0.3	V
V_{OH}	High-level output voltage	I_{OH} = –21 mA	–40°C	–1.26		–0.9	V
			25°C	–1.2		–0.9	
			85°C	–1.15		–0.9	

(1) VIN_{PP} minimum and maximum is required to maintain ac specifications, actual device function tolerates a minimum VIN_{PP} of 100 mV.

LVECL DC ELECTRICAL CHARACTERISTICS (continued)

Vsupply: V_{CC} = 0 V, V_{EE} = -2.375 V to -3.8 V

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{OL}	Low-level output voltage	I_{OL} = –5 mA	–40°C	–1.85		–1.5	V
			25°C	–1.85		–1.45	
			85°C	–1.85		–1.4	
V_{OD}	Differential output voltage swing	Terminated with 50 Ω to V_{CC} – 2 V, See Figure 3	–40°C, 25°C, 85°C	600			V

LVPECL/HSTL DC ELECTRICAL CHARACTERISTICS

Vsupply: V_{CC} = 2.375 V to 3.8 V, V_{EE}= 0 V

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
I_{EE}	Supply internal current	Absolute value of current	–40°C	40		78	mA
			25°C	45		82	
			85C	48		85	
I_{CC}	Output and internal supply current	All outputs terminated 50 Ω to V_{CC} – 2 V	–40°C			343	mA
			25°C			370	
			85°C			380	
I_{IN}	Input current		–40°C, 25°C, 85°C			150	µA
V_{BB}	Internally generated bias voltage	V_{EE} = –3 to –3.8 V, I_{BB}= –0.2 mA	–40°C, 25°C, 85°C	V_{CC} – 1.45	V_{CC} – 1.3	V_{CC} – 1.15	V
		V_{EE} = –2.375 to –2.75 V, I_{BB} = -0.2 mA	–40°C, 25°C, 85°C	V_{CC}– 1.4	V_{CC} – 1.25	V_{CC} – 1.1	
V_{IH}	High-level input voltage (CLK_SEL)		–40°C, 25°C, 85°C	V_{CC} - 1.165		V_{CC} – 0.88	V
V_{IL}	Low-level input voltage (CLK_SEL)		–40°C, 25°C, 85°C	V_{CC} - 1.81		V_{CC} – 1.475	V
VIN_{PP}	Input amplitude (CLK0, $\overline{CLK0}$)	Difference of input 9 V_{IH}–V_{IL}, see Note (1)	–40°C, 25°C, 85°C	0.5		1.3	V
V_{IC}	Common-mode voltage (CLK0, $\overline{CLK0}$)	Cross point of input 9 average (V_{IH}, V_{IL})	–40°C, 25°C, 85°C	0.975		V_{CC} – 0.3	V
V_{ID}	Differential input voltage (CLK1, $\overline{CLK1}$)	Difference of input V_{IH}–V_{IL}, See Note (1)	–40°C, 25°C, 85°C	0.4		1.9	V
$V_{I(x)}$	Input crossover voltage (CLK1, $\overline{CLK1}$)	Cross point of input 9 average (V_{IH}, V_{IL})	–40°C, 25°C, 85°C	0.68		0.9	V
V_{OH}	High-level output voltage	I_{OH} = –21 mA	–40°C	V_{CC} – 1.26		V_{CC} – 0.9	V
			25°C	V_{CC} – 1.2		V_{CC} – 0.9	
			85°C	V_{CC} - 1.15		V_{CC} - 0.9	
V_{OL}	Low-level output voltage	I_{OL} = –5 mA	-40°C	V_{CC} - 1.85		V_{CC} - 1.5	V
			25°C	V_{CC} - 1.85		V_{CC} - 1.45	
			85°C	V_{CC} - 1.85		V_{CC} - 1.4	
V_{OD}	Differential output voltage swing	Terminated with 50 Ω to V_{CC} – 2 V, See Figure 4	-40°C, 25°C, 85°C	600			mV

(1) VIN_{PP} minimum and maximum is required to maintain ac specifications, actual device function tolerates a minimum VIN_{PP} of 100 mV.

AC ELECTRICAL CHARACTERISTICS

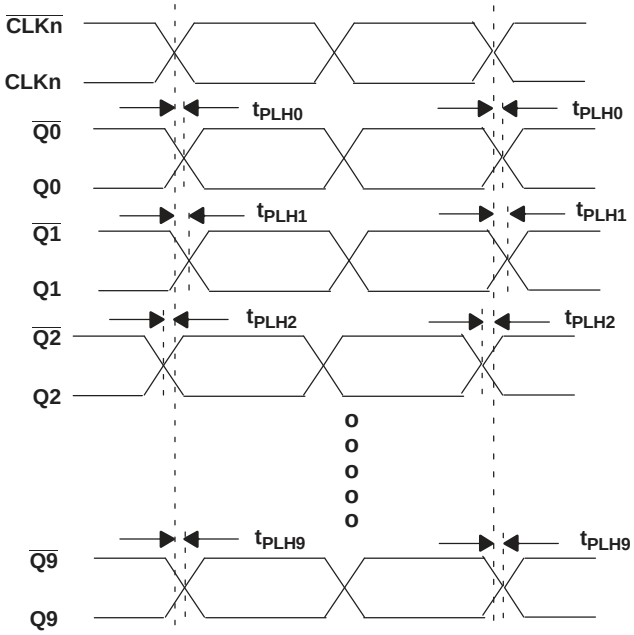
Vsupply: V_{CC} = 2.375 V to 3.8 V, V_{EE} = 0 V or LVECL/LVPECL input V_{CC} = 0 V, V_{EE} = -2.375 V to -3.8 V

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{pd}	Differential propagation delay CLK0, $\overline{CLK0}$ to all Q0, $\overline{Q0}$… Q9, $\overline{Q9}$	Input condition: VCM = 1 V, V_{PP} = 0.5 V	–40°C, 25°C, 85°C	230		350	ps
$t_{sk(pp)}$	Part-to-part skew	See Note B and Figure 1	–40°C, 25°C, 85°C			70	ps
$t_{sk(o)}$	Output-to-output skew	See Note A and Figure 1	–40°C, 25°C, 85°C		15	30	ps
$t_{(JITTER)}$	Cycle-to-cycle RMS jitter		–40°C, 25°C, 85°C			< 1	ps
$f_{(max)}$	Maximum frequency	Functional up to 3.5 GHz, timing specifications apply at 1 GHz, see Figure 3	–40°C, 25°C, 85°C			3500	MHz
t_r/t_f	Output rise and fall time (20%, 80%)		–40°C, 25°C, 85°C	100		200	ps

HSTL INPUT

Vsupply: V_{CC} = 2.375 V to 3.8 V, V_{EE} = 0 V

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{pd}	Differential propagation delay CLK0, $\overline{CLK0}$ to all Q0, $\overline{Q0}$… Q9, $\overline{Q9}$	Input condition: V_x = 0.68 V, V_{dif} = 0.4 V	–40°C, 25°C, 85°C	290		370	ps
$t_{sk(pp)}$	Part-to-part skew	See Note B and Figure 1	–40°C, 25°C, 85°C			70	ps
$t_{sk(o)}$	Output to output skew	See Note A and Figure 1	–40°C, 25°C, 85°C		10	30	ps
$t_{(JITTER)}$	Cycle-to-cycle RMS jitter		–40°C, 25°C, 85°C			<1	ps
$f_{(max)}$	Maximum frequency	Functional up to 3.5 GHz, timing specifications apply at 1 GHz, See Figure 4	–40°C, 25°C, 85°C			3500	MHz
t_r/t_f	Output rise and fall time (20%, 80%)		–40°C, 25°C, 85°C	100		200	ps



A. Output skew is calculated as the greater of: The difference between the fastest and the slowest t_{PLHn} (n = 0, 1,...9) or the difference between the fastest and the slowest t_{PHLn} (n = 0, 1,...9).

B. Part-to-part skew, is calculated as the greater of: The difference between the fastest and the slowest t_{PLHn} (n = 0, 1,...9) across multiple devices or the difference between the fastest and the slowest t_{PHLn} (n = 0, 1,...9) across multiple devices.

Figure 1. Waveform for Calculating Both Output and Part-to-Part Skew

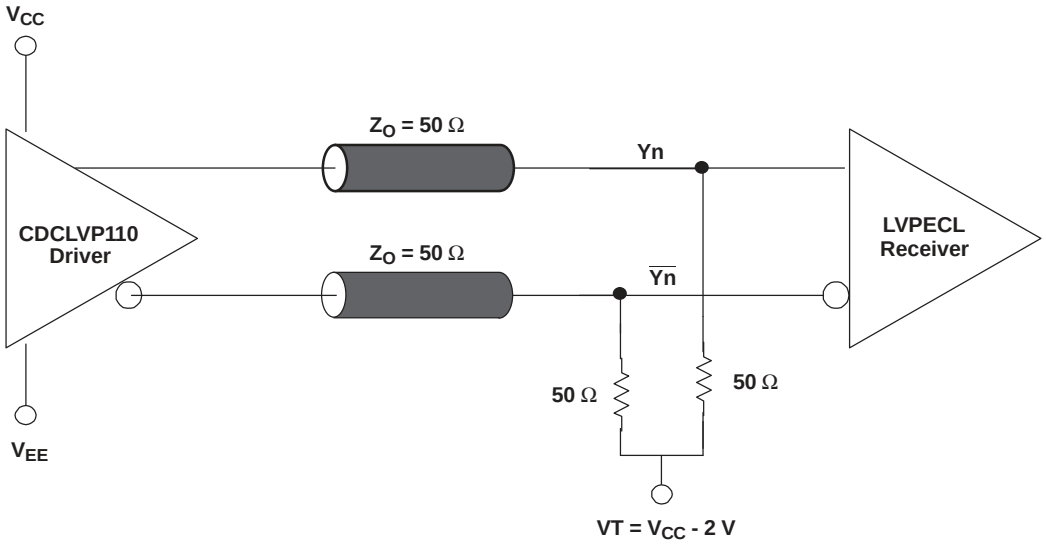


Figure 2. Typical Termination for Output Driver (See the Interfacing Between LVPECL, LVDS, and CML Application Note, Literature Number SCAA056)

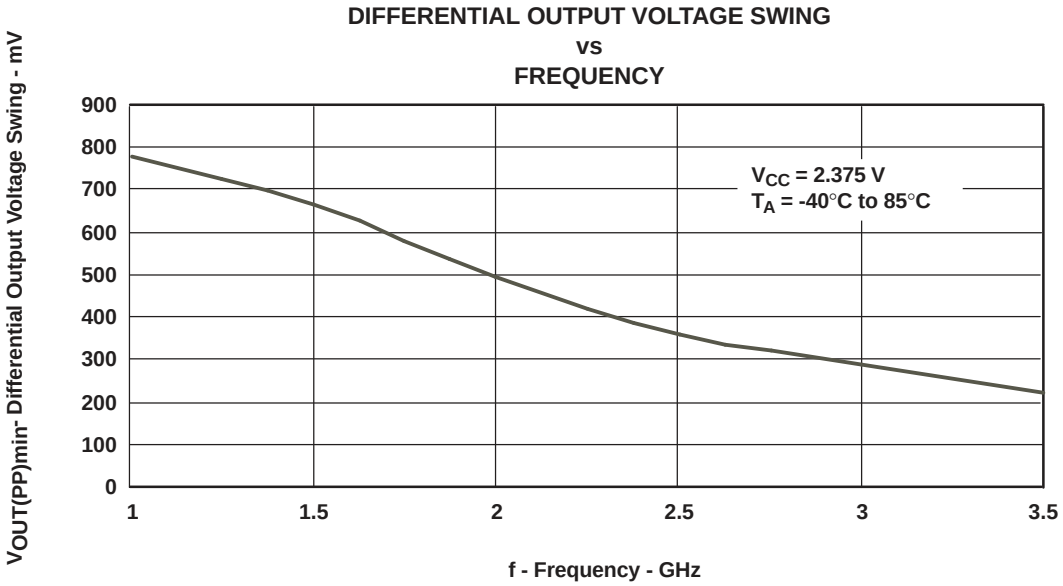


Figure 3. LVPECL Input Using CLK0 Pair, VCM = 1 V, VIN_{dif} = 0.5 V

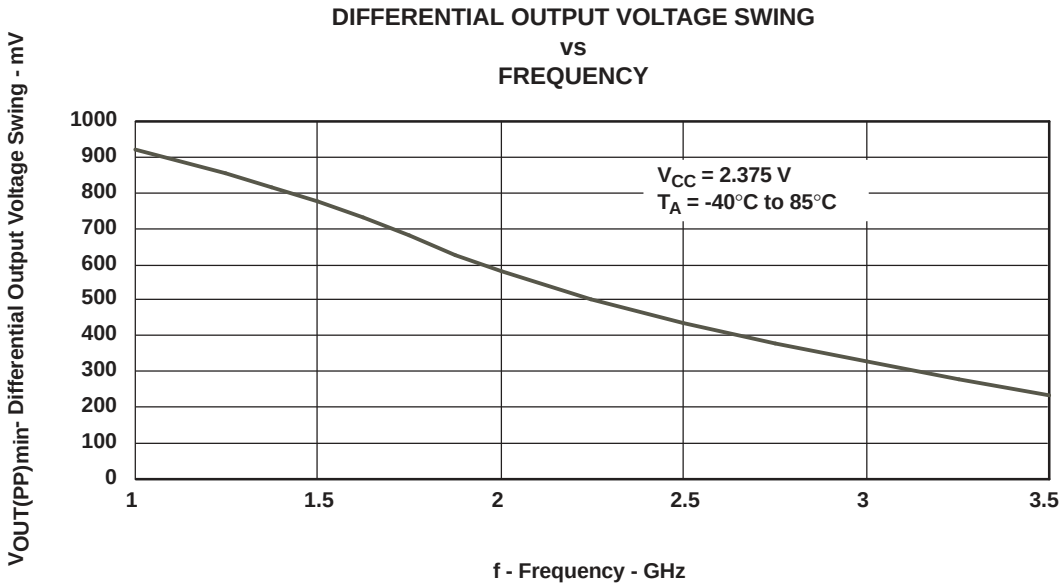


Figure 4. HSTL Input Using CLK1 Pair, VCM = 0.68 V, VIN_{dif} = 0.4 V

REVISION HISTORY

Changes from Revision A (August 2002) to Revision B **Page**

- Changed PACKAGE THERMAL IMPEDANCE max values 3
- Deleted I_{IN} test condition 3
- Deleted I_{IN} test condition 4

Changes from Revision B (January 2010) to Revision C **Page**

- Changed LVECL DC spec for V_{BB} (V_{EE} = –3 to –3.8 V) from 3 rows to 1 row and added TYP value. 3
- Changed LVECL DC spec for V_{BB} (V_{EE} = –2.375 to –2.75 V); MIN value from –1.38 V to –1.4 V, MAX from –1.16 V to –1.1 V, and added TYP value of –1.25 V 3
- Changed LVECL/HSTL DC spec for V_{BB} (V_{EE} = –3 to –3.8 V) from 3 rows to 1 row and added TYP value. 4
- Changed LVECL/HSTL DC spec for V_{BB} (V_{EE} = –2.375 to –2.75 V); MIN value from V_{CC} –1.38 V to V_{CC} –1.4 V; MAX from V_{CC} –1.16 V to V_{CC} –1.1 V; and added TYP value of V_{CC} –1.25 V 4

Changes from Revision C (January 2011) to Revision D **Page**

- Changed V_{CM} spec from V_{EE}+1 to V_{EE}+0.975 3
- Changed V_{IC} spec from 1 to 0.975 4

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CDCLVP110MVFR	ACTIVE	LQFP	VF	32	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CDCLVP110	Samples
CDCLVP110VF	ACTIVE	LQFP	VF	32	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CDCLVP110	Samples
CDCLVP110VFG4	ACTIVE	LQFP	VF	32	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CDCLVP110	Samples
CDCLVP110VFR	ACTIVE	LQFP	VF	32	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CDCLVP110	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

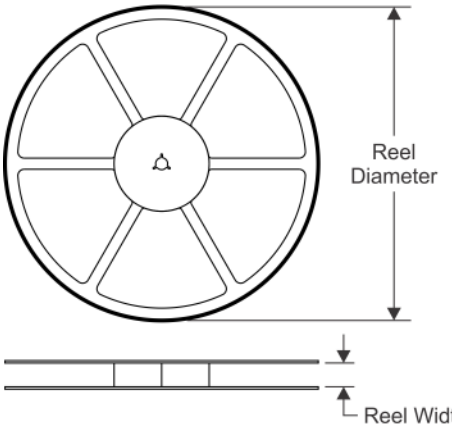
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals.
TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

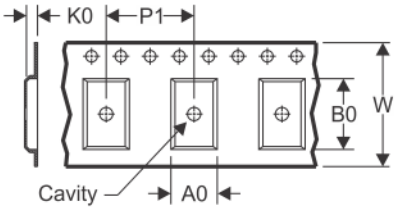
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

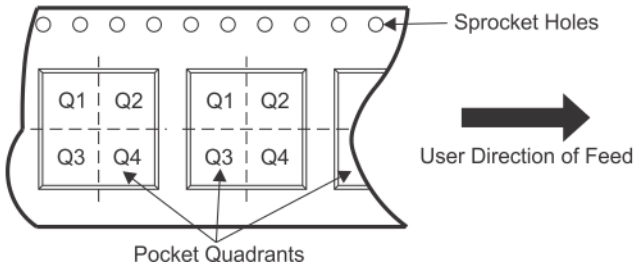


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

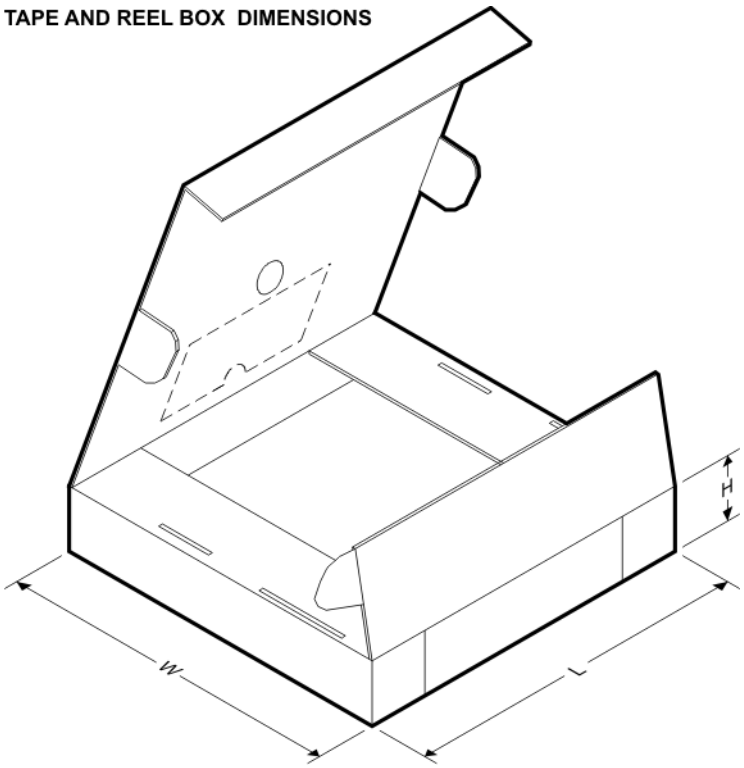
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDCLVP110MVFR	LQFP	VF	32	1000	330.0	16.4	9.6	9.6	1.9	12.0	16.0	Q1
CDCLVP110VFR	LQFP	VF	32	1000	330.0	16.4	9.6	9.6	1.9	12.0	16.0	Q2

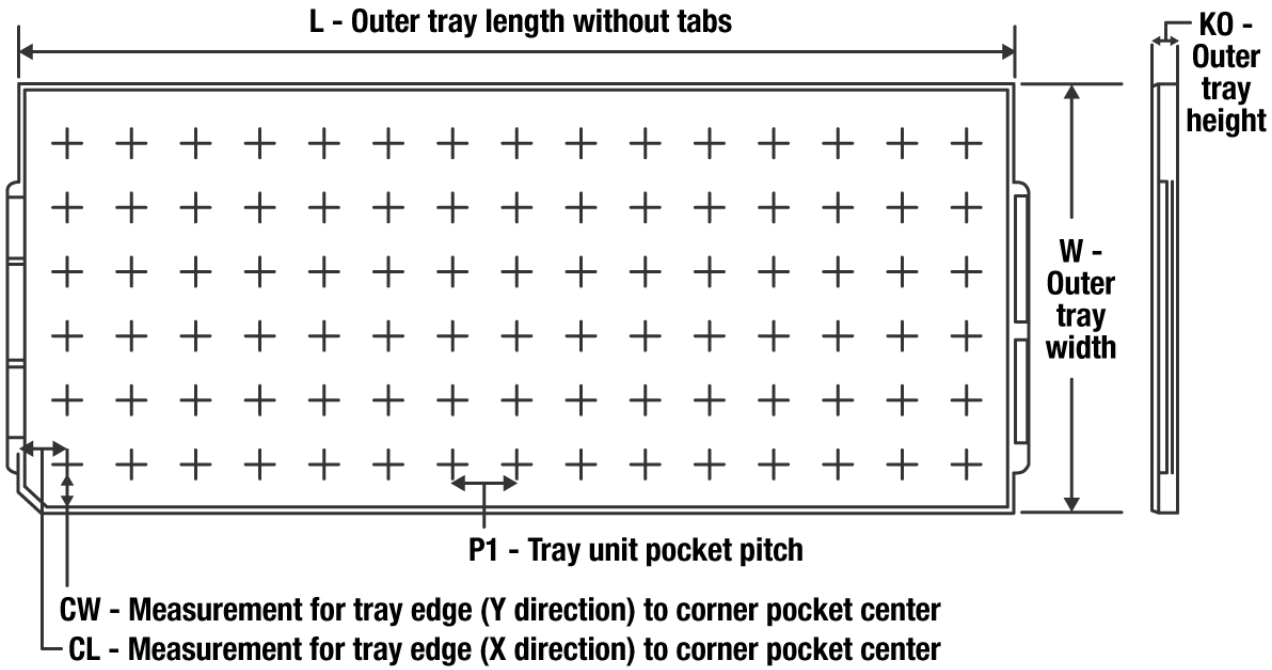
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDCLVP110MVFR	LQFP	VF	32	1000	367.0	367.0	38.0
CDCLVP110VFR	LQFP	VF	32	1000	367.0	367.0	38.0

TRAY



Chamfer on Tray corner indicates Pin 1 orientation of packed units.

*All dimensions are nominal

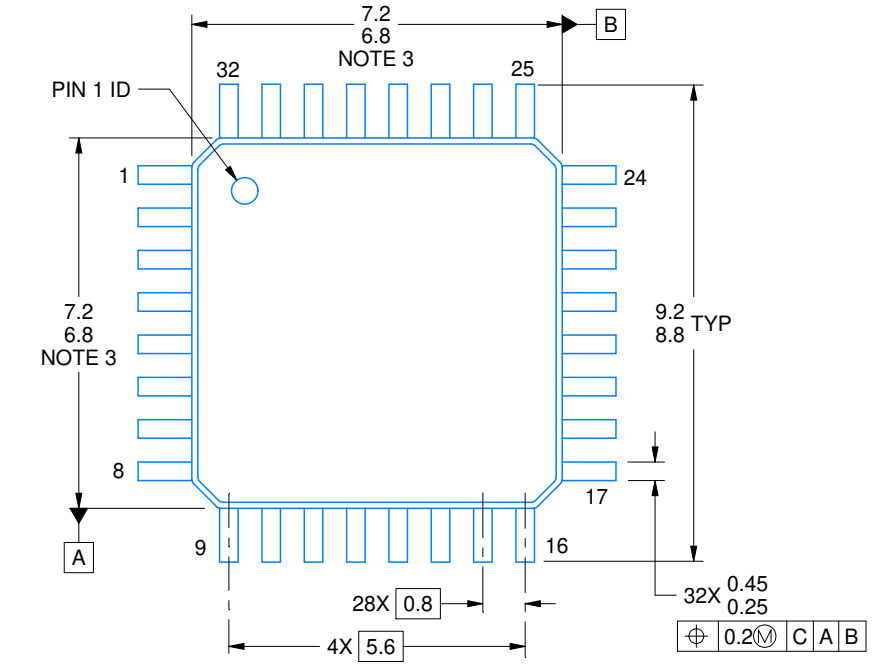
Device	Package Name	Package Type	Pins	SPQ	Unit array matrix	Max temperature (°C)	L (mm)	W (mm)	K0 (µm)	P1 (mm)	CL (mm)	CW (mm)
CDCLVP110VF	VF	LQFP	32	250	10 x 25	150	315	135.9	7620	12.2	11.1	11.25
CDCLVP110VFG4	VF	LQFP	32	250	10 x 25	150	315	135.9	7620	12.2	11.1	11.25

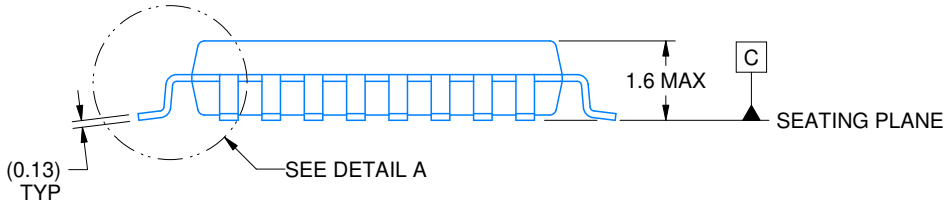
PACKAGE OUTLINE

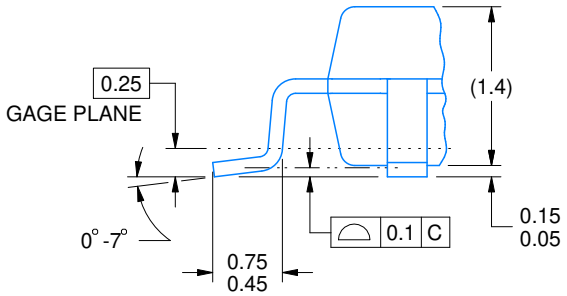
VF0032A

LQFP - 1.6 mm max height

PLASTIC QUAD FLATPACK







DETAIL A
TYPICAL

4219769/A 04/2019

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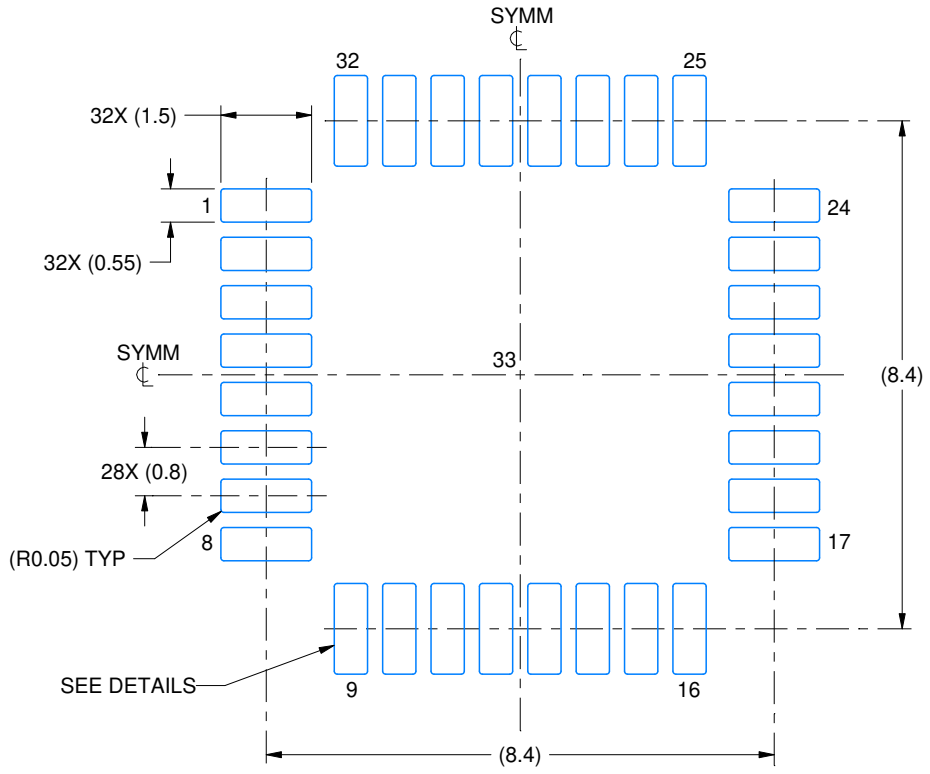
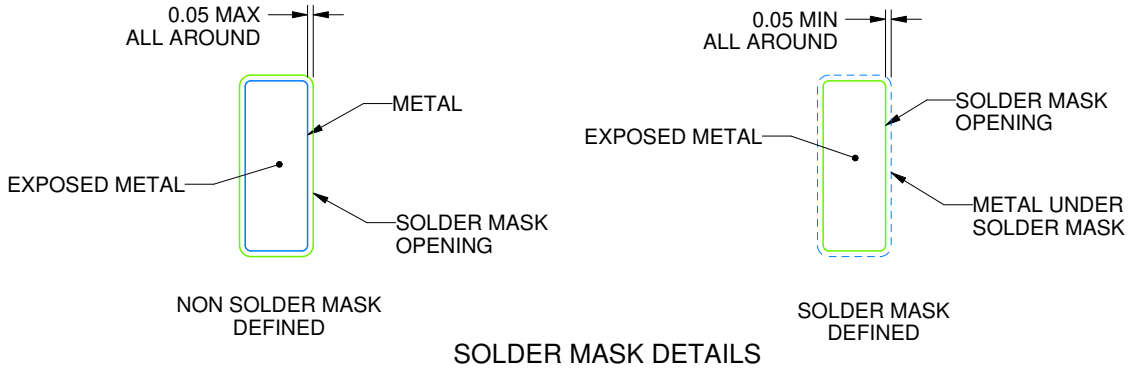
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs.
4. Reference JEDEC registration MS-026.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X

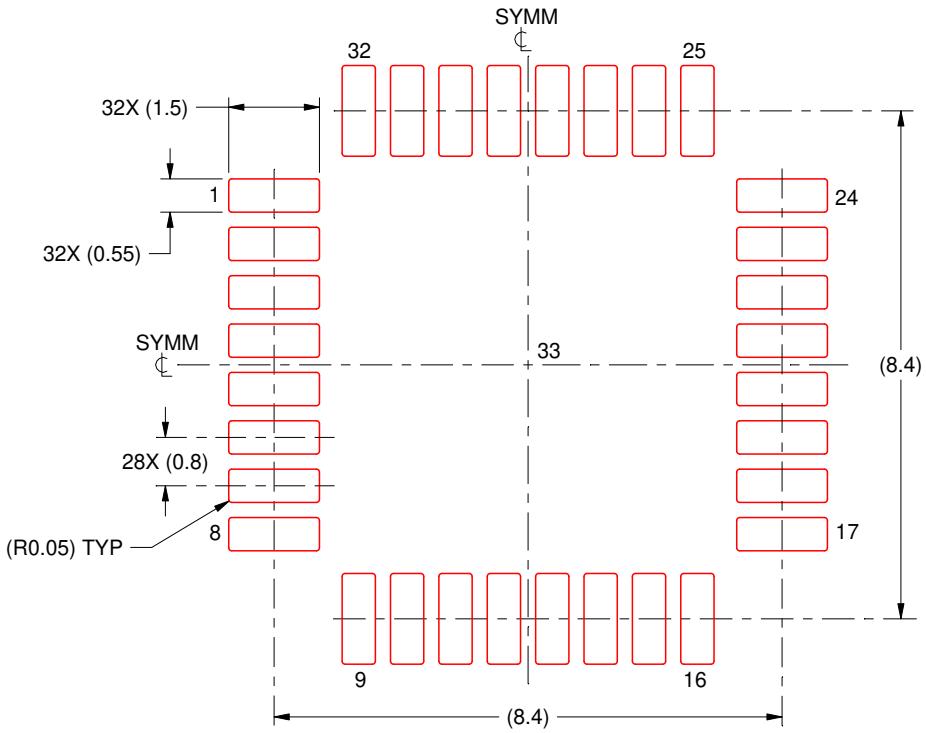


SOLDER MASK DETAILS

4219769/A 04/2019

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
SCALE:8X

4219769/A 04/2019

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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